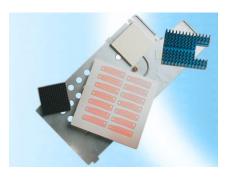


Tpli 200 Series Thermal Gap Filler



*Ready for 5G

PRODUCT DESCRIPTION

Tpli[™] 200 is a premium gap filler. A unique blend of boron nitride and silicone produce the highest performing interface pad.

Tpli 200's exceptional combination of high thermal conductivity and compliancy generate unmatched thermal resistances in a gap filling interface material.

Tpli 200 absorbs shock and relieves stresses, thus minimizing potential damage to components. Tpli 200 is electrically insulating, stable from -45°C to 200°C, and meets UL 94 HB rating.

FEATURES AND BENEFITS

- Soft and compliant
- High Thermal performance
- Environmentally friendly solution that meets regulatory requirements including RoHS and REACH

SPECIFICATIONS

| TYPICAL PROPERTIES | TYPICAL VALUE | TEST METHOD |
|-------------------------------|-------------------------------------|-------------|
| Construction & Composition | Boron nitride filled silicone sheet | N/A |
| Color | Varies by thickness | Visual |
| Thickness Range | 0.25mm (0.010") - 5.08mm (0.20") | N/A |
| Thickness Tolerance | +/- 10% | N/A |
| Thermal Conductivity (W/mK) | 6.0 | ASTM D5470 |
| Density (g/cc) | 1.4 | Helium |
| | | Pyncometer |
| Hardness (Shore 00) | 70 | ASTM D2240 |
| Outgassing TML (weight %) | 0.51 | ASTM E595 |
| Outgassing CVCM (weight %) | 0.17 | ASTM E595 |
| Temperature Range | -45°C to 200°C | N/A |
| Rth@ 40 mils, 10 psi, 50°C | 0.25°C-in2/W | ASTM D5470 |
| | | (modified) |
| * Dielectric Constant @ 10GHz | 3.2 * | ASTM D150 |
| UL Flammability Rating | НВ | UL 94 |
| Volume Resistivity | 5x10^13 ohm-cm | ASTM D257 |
| | | |

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Tpli 200 Series Thermal Gap Filler

AVAILABILITY

STANDARD THICKNESSES

- 0.25mm (0.010") to 5.0mm (0.200") thick material available in 0.25mm (0.010") increments
- Available in standard sheet sizes of 18" x 18" and 9" x 9" or custom die cut parts

REINFORCEMENT

- Fiberglass is required in thicknesses of 0.010" (0.25mm) and 0.015" (0.38mm)
- Reinforcement is optional in thicknesses 0.020" (0.5mm) and 0.025" (0.63mm). Indicate fiberglass by "FG" suffix
- Thicknesses above 0.025" (0.063mm) are not reinforced

OPTIONS

- A0 no adhesive
- A1 adhesive on one side

POST CURE

Post Curing option available. Indicate fiberglass by "PC" suffix

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. Tpli 2xx indicates Tpli 200 product line with thickness in mils (0.001")

EXAMPLES:

- Tpli 240,A0 = 0.040 inch thick Tpli™ 200 material with no adhesive
- Tpli 280,A1 = 0.080 inch thick Tpli™ 200 material with one side adhesive
- Tpli 220FG,A1 = 0.020 inch thick Tpli™ 200 material with fiberglass reinforcement and one side adhesive
- Tpli 260,PC = 0.060 inch thick Tpli™ 200 material post cured

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